Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.75 (3.1 EP)
Lead Count	20
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.52E-02	86.2	862000	38.63	386305
Thermosets	Epoxy resin	Proprietary	2.45E-03	6.0	60000	2.69	26889
Thermosets	Phenol resin	Proprietary	2.45E-03	6.0	60000	2.69	26889
Other inorganic materials	Metal Hydroxide	Proprietary	6.13E-04	1.5	15000	0.67	6722
Other inorganic materials	Carbon black	1333-86-4	1.23E-04	0.3	3000	0.13	1344
Subtotal			4.09E-02	100.00	1000000	44.82	448150

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.33 E-02	97.5	975000	47.46	474629
Copper & its alloys	Iron	7439-89-6	1.04 E-03	2.35	23500	1.14	11440
Copper & its alloys	Zinc	7440-66-6	5.33 E-05	0.12	1200	0.06	584
Copper & its alloys	Phosphorus	7723-14-0	1.33 E-05	0.03	300	0.01	146
Subtotal			4.44 E-02	100.00	1000000	48.68	486799

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.45 E-05	100.0	1000000	0.05	487

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.10 E-03	100.0	1000000	2.30	23021

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.57 E-04	100.0	1000000	0.17	1723

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.17 E-03	100.0	1000000	3.48	34767

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.06 E-04	66.34	663400	0.34	3351
Thermoset	Epoxy resin	Proprietary	2.59 E-05	5.61	56100	0.03	283
Other organic materials	Aliphatic acid anhydride	Proprietary	2.59 E-05	5.61	56100	0.03	283
Other organic materials	2,6 diglycidyl phenyl allyl ether oligomer	Proprietary	2.59 E-05	5.61	56100	0.03	283
Other organic materials	Epoxy derivative	Proprietary	2.59 E-05	5.61	56100	0.03	283
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	2.59 E-05	5.61	56100	0.03	283
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	2.59 E-05	5.61	56100	0.03	283
Subtotal			4.61 E-04	100.0	1000000	0.51	5052

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.12 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary